



Click [here](#) for the 3D model.

General Information

Series	SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	190 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	2220
L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
T	1.7mm +/-0.15mm
S	3.5mm MIN
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

Specifications

Capacitance	0.47 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	2.1277 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.